CLAIM AMENDMENTS

1. (Currently Amended) A method of manufacturing a device package in which a device is electrically connected to external wiring through a metal wire, said the method comprising:

forming a small-diameter ball by using a small-diameter metal wire, bonding said small-diameter ball to said the device, and then separating said small-diameter metal wire from said small-diameter ball;

forming a large-diameter ball by using a large-diameter metal wire, and bonding said large-diameter ball to said the external wiring, said small-diameter ball and metal wire having respective diameters smaller than respective diameters of said large-diameter ball and metal wire; and

bonding said large-diameter metal wire eonnecting with connected to said large-diameter ball to said small-diameter ball by stitch bonding, and then separating said large-diameter metal wire from said small-diameter ball.

- 2. (Original) The method according to claim 1, wherein the diameter of said largediameter metal wire is approximately equal to the diameter of said small-diameter ball.
- 3. (Currently Amended) The method according to claim 2, wherein said large-diameter metal wire is bonded to said small-diameter ball such so that the height of the a top portion of said large-diameter metal wire is approximately equal to the height co-planar with a top portion of said small-diameter ball.
 - 4. (Currently Amended) A device package in-which a comprising:
- <u>a</u> device is electrically connected to external wiring through a metal wire, said device package comprising:
 - a small-diameter ball which is bonded to said device; and
- a large-diameter ball which is, having a larger diameter than said small-diameter ball, bonded to said the external wiring; wherein said small-diameter ball is connected to said large-diameter ball through said metal wire while the height of and said small-diameter ball is approximately equal to the height of co-planar with said metal wire.